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INA27x Voltage Output, Unidirectional Measurement Current-Shunt Monitor

Technical

Documents

1 Features

- Wide Common-Mode Range: -16 V to +80 V
- CMRR: 120 dB
- Accuracy: ±0.5-mV Offset (typ) ±0.2% Gain Error (typ) 2.5 μV/°C Offset Drift (typ) 50 ppm/°C Gain Drift (max)
- Bandwidth: Up to 130 kHz
- Two Gain Options Available: 14 V/V (INA270) 20 V/V (INA271)
- Quiescent Current: 700 μA (typ)
- Power Supply: +2.7 V to +18 V
- Provision for Filtering

2 Applications

- Power Management
- Automotive
- Telecom Equipment
- Notebook Computers
- Battery Chargers
- Cell Phones
- Welding Equipment

3 Description

The INA270 and INA271 family of voltage-output, current-sense amplifiers can sense drops across shunt resistors at common-mode voltages from -16 V to +80 V, independent of the supply voltage. The INA270 and INA271 pinouts readily enable filtering.

The INA270 and INA271 are available with two gain options: 14 V/V and 20 V/V. The 130-kHz bandwidth simplifies use in current-control loops.

The INA270 and INA271 operate from a single +2.7-V to +18-V supply, drawing 700 μ A (typical) of supply current. The devices are specified over the extended operating temperature range of -40°C to +125°C and are offered in an SOIC-8 package.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
INA27x	SOIC (8)	4.90 mm × 3.91 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Rs -16V to +80V 0 MΛ I oad Supply Single-Pole Filter Capacitor +2.7V to +18V BUF IN PRE OUT IN-IN-V+ \ge 5k Ω \ge 5k Ω ₩V-≥ 96k Ω ≷ R_L INA270 GND

Simplified Schematic

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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	hanges from Revision D (November 2014) to Revision E	Page
•	Added title to page 1 figure	1
•	Updated ESD Ratings table to current standards	4
•	Changed Figure 16: changed op amp input to BUF IN pin from negative to positive	12
•	Added Community Resources section	19

Changes from Revision C (May 2010) to Revision D

•	Changed format to meet latest data sheet standards 1
•	Added Handling Rating, Pin Descriptions, and Recommended Operating Conditions tables and Feature Description, Device Functional Modes, Application and Implementation, Power Supply Recommendations, Layout, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information sections
•	Changed Accuracy and Quiescent Current Features bullets: changed from max specifications and values to typical 1
•	Changed wording in Two Gain Options Available Features bullet 1
•	Changed Description section for clarification 1
•	Added Device Information table 1
•	Deleted Ordering Information table 3
•	Changed Input, Full-Scale Input Voltage parameter conditions in Electrical Characteristics table
•	Changed title of First- or Second-Order Filtering section 12
•	Changed title of Power Supply Recommendations section

Cł	hanges from Revision B (July 2008) to Revision C		
•	Corrected Figure 17 y-axis	. 14	
•	Corrected Figure 18 y-axis	. 14	

EXAS **NSTRUMENTS**

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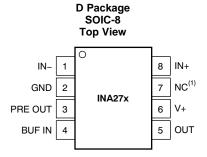
Page



5 Device Comparison Table

DEVICE	GAIN
INA270	14 V/V
INA271	20 V/V

6 Pin Configuration and Functions



NOTE (1): NC denotes no internal connection.

Pin Functions

PIN		1/0	DESCRIPTION	
NAME	NO.	I/O	DESCRIPTION	
BUF IN	4	Analog input	Connect to output of filter from PRE OUT	
GND	2	Analog	Ground	
IN-	1	Analog input	nput Connect to load side of shunt resistor	
IN+	8	Analog input	Connect to supply side of shunt resistor	
NC	7	—	— Connect to ground	
OUT	5	Analog output	Output voltage	
PRE OUT	3	Analog output	alog output Connect to input of filter to BUF IN	
V+	6	Analog input	nput Power supply, +2.7 V to +18 V	

7 Specifications

7.1 Absolute Maximum Ratings⁽¹⁾

		MIN	MAX	UNIT
Supply voltage (V _S)			+18	V
	Differential, $(V_{IN+}) - (V_{IN-})$	-18	+18	V
Analog inputs, V _{IN+} , V _{IN-} :	Common-mode	-16	+80	V
Analog output: OUT and PRE OUT pins		GND – 0.3	(V+) + 0.3	V
Input current into any pin			5	mA
Operating temperature		-55	+150	°C
Junction temperature			+150	°C
Storage temperature, T _{stg}		-65	+150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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STRUMENTS

EXAS

7.2 ESD Ratings

			VALUE	UNIT
	Electrostatia discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±3000	±3000
V _(ESD)	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±750	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _{CM}	Common-mode input voltage	-16	12	80	V
Vs	Operating supply voltage	2.7	5	18	V
T _A	Operating free-air temperature	-40		125	°C

7.4 Thermal Information

		INA27x	
	THERMAL METRIC ⁽¹⁾	D (SOIC)	UNIT
		8 PINS	
$R_{ hetaJA}$	Junction-to-ambient thermal resistance	78.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	71.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	68.2	°C/W
ΨJT	Junction-to-top characterization parameter	22.0	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	67.6	°C/W
R _{0JC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



7.5 Electrical Characteristics

At $T_{A} = +25^{\circ}$ C, $V_{S} = +5$ V, $V_{CM} = +12$ V, $V_{SENSF} = 100$ mV, and PRE OUT connected to BUF IN, unless otherwise noted.

	PARAME	ETER	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
INPUT							
V _{SENSE}	Full-scale input v	oltage	$V_{\text{SENSE}} = (V_{\text{IN+}}) - (V_{\text{IN-}})$		0.15 (\	/ _S – 0.2) / Gain	V
V _{CM}	Common-mode in	nput range	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$	-16		+80	V
CMRR	Common-mode r	ejection ratio	V _{IN+} = -16 V to +80 V	80	120		dB
	CMRR over temp	perature	V _{IN+} = +12 V to +80 V, T _A = -40°C to +125°C	100	120		dB
V _{OS}	Offset voltage, R	TI ⁽¹⁾			±0.5	2.5	mV
	V _{OS} over tempera	ature	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			±3	mV
dV _{OS} /dT	V _{OS} vs temperatu	ıre	$T_A = -40^{\circ}C$ to $+125^{\circ}C$		2.5	20	μV/°C
PSR	V _{OS} vs power-su	pply	$V_{S} = +2.7 \text{ V to } +18 \text{ V}, V_{CM} = +18 \text{ V},$ $T_{A} = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		5	100	μV/V
I _B	Input bias current, V _{IN} pin		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$		±8	±16	μΑ
	PRE OUT output impedance ⁽²⁾				96		kΩ
	Buffer input bias current				-50		nA
	Buffer input bias coefficient	current temperature			±0.03		nA/°C
OUTPUT	(V _{SENSE} ≥ 20mV) ⁽³⁾						
G	Coin	INA270 total gain			14		V/V
	Gain	INA271 total gain			20		V/V
G _{BUF}	Output buffer gai	n			2		V/V
	Total gain error		V _{SENSE} = 20 mV to 100 mV		±0.2%	±1%	
	Total gain error C	Over temperature	$T_A = -40$ °C to +125°C			±2%	
	Total gain error v	s temperature	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			50	ppm/°C
	Total output error ⁽⁴⁾				±0.75%	±2.2%	
	Total output error	r	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$		±1.0%	±3.0%	
	Nonlinearity error	r	$V_{SENSE} = 20 \text{ mV} \text{ to } 100 \text{ mV}$		±0.002%		
Ro	Output impedance	e, pin 5			1.5		Ω
	Maximum capaci	tive load	No sustained oscillation		10		nF
VOLTAGE	E OUTPUT ⁽⁵⁾ (R _L =	10 kΩ to GND)					
	Swing to V+ pow	er-supply rail	$T_A = -40$ °C to +125°C		(V+) – 0.05	(V+) – 0.2	V
	Swing to GND ⁽⁶⁾		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$	V	_{GND} + 0.003	V_{GND} + 0.05	V
FREQUE	NCY RESPONSE						
BW	Bandwidth		C _{LOAD} = 5 pF		130		kHz
	Phase margin		C _{LOAD} < 10 nF		40		Degrees
SR	Slew rate				1		V/µs
t _S	Settling time (1%)	V_{SENSE} = 10 mV to 100 mV _{PP} , C _{LOAD} = 5 pF		2		μS

(1) RTI means Referred-to-Input.

Initial resistor variation is ±30% with an additional -2200-ppm/°C temperature coefficient. (2)

For output behavior when V_{SENSE} < 20 mV, see the Accuracy Variations as a Result of V_{SENSE} and Common-Mode Voltage section. Total output error includes effects of gain error and V_{OS} . (3)

(4)

See typical characteristic curve Output Swing vs Output Current and the Accuracy Variations as a Result of VSENSE and Common-Mode (5) Voltage section.

(6) Ensured by design; not production tested.



Electrical Characteristics (continued)

At $T_A = +25^{\circ}C$, $V_S = +5 V$, $V_{CM} = +12 V$, $V_{SENSE} = 100 \text{ mV}$, and PRE OUT connected to BUF IN, unless otherwise noted.

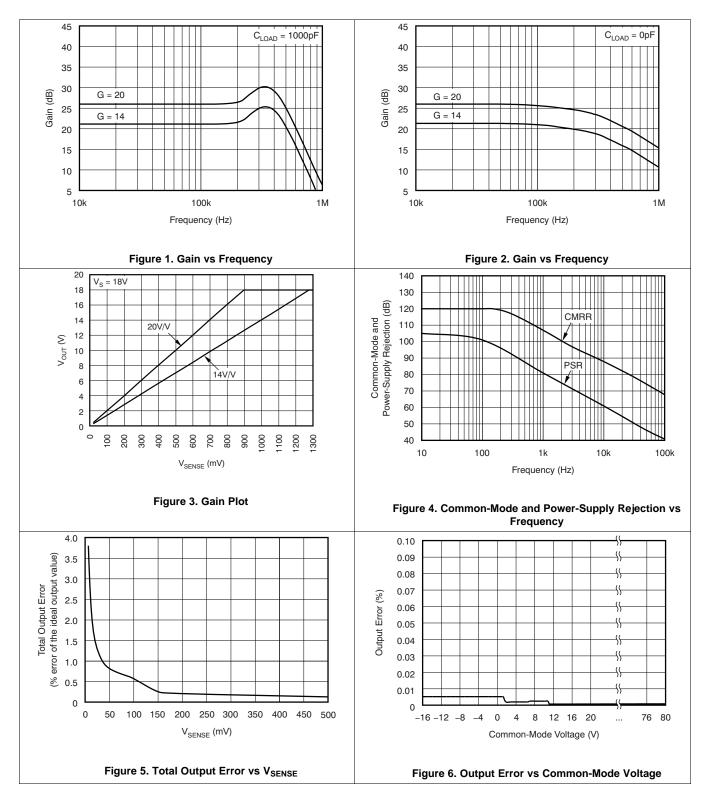
	PARAMETER	PARAMETER TEST CONDITIONS		ТҮР	MAX	UNIT
NOISE,	, RTI ⁽¹⁾					
en	Voltage noise density			40		nV/√Hz
POWER	R SUPPLY					
Vs	Operating range	$T_A = -40^{\circ}C$ to $+125^{\circ}C$	+2.7		+18	V
Ι _Q	Quiescent current	$V_{OUT} = 2 V$		700	900	μΑ
	I _Q over temperature	$V_{SENSE} = 0 \text{ mV}, \text{T}_{A} = -40^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}$		350	950	μA
TEMPE	RATURE RANGE		•			
	Specified temperature range		-40		+125	°C
	Operating temperature range		-55		+150	°C
θ_{JA}	Thermal resistance, SO-8			150		°C/W

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7.6 Typical Characteristics

At T_A = +25°C, V_S = +12 V, V_{CM} = 12 V, and V_{SENSE} = 100 mV, unless otherwise noted.

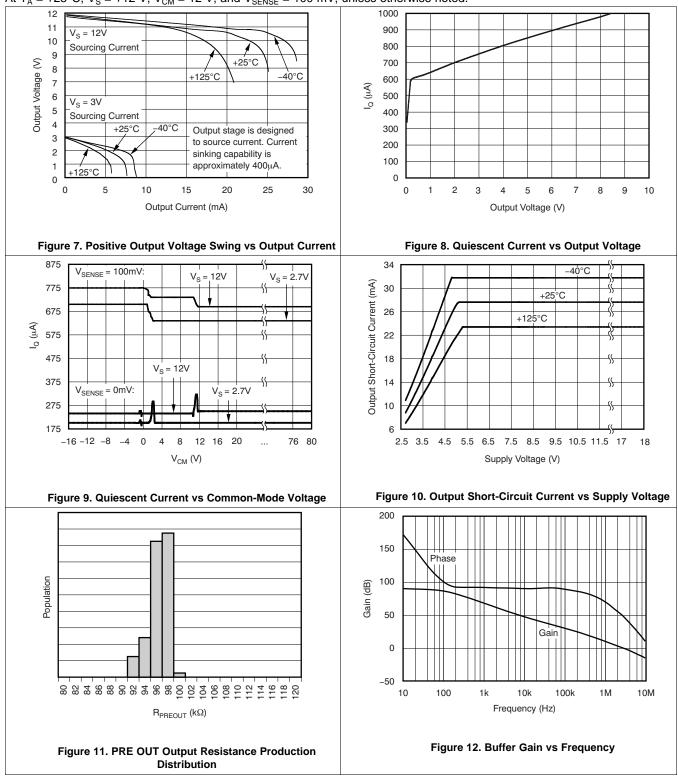


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Typical Characteristics (continued)

At $T_A = +25^{\circ}$ C, $V_S = +12$ V, $V_{CM} = 12$ V, and $V_{SENSE} = 100$ mV, unless otherwise noted.

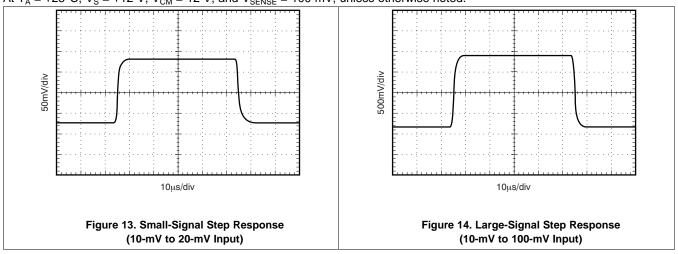




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Typical Characteristics (continued)



At $T_A = +25^{\circ}C$, $V_S = +12$ V, $V_{CM} = 12$ V, and $V_{SENSE} = 100$ mV, unless otherwise noted.



8 Detailed Description

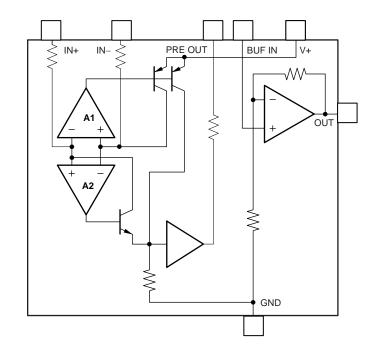
8.1 Overview

The INA270 and INA271 family of current-shunt monitors with voltage output can sense drops across current shunts at common-mode voltages from -16 V to +80 V, independent of the supply voltage. The INA270 and INA271 pinouts readily enable filtering.

The INA270 and INA271 are available with two output voltage scales: 14 V/V and 20 V/V. The 130-kHz bandwidth simplifies use in current-control loops.

The INA270 and INA271 operate from a single +2.7-V to +18-V supply, drawing a maximum of 900 μ A of supply current. The devices are specified over the extended operating temperature range of -40°C to +125°C and are offered in an SOIC-8 package.

8.2 Functional Block Diagram





8.3 Feature Description

8.3.1 Basic Connection

Figure 15 shows the basic connection of the INA270 and INA271. Connect the input pins (IN+ and IN–) as closely as possible to the shunt resistor to minimize any resistance in series with the shunt resistance.

Power-supply bypass capacitors are required for stability. Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise. Place minimum bypass capacitors of 0.01 μ F and 0.1 μ F in value close to the supply pins. Although not mandatory, an additional 10-mF electrolytic capacitor placed in parallel with the other bypass capacitors may be useful in applications with particularly noisy supplies.

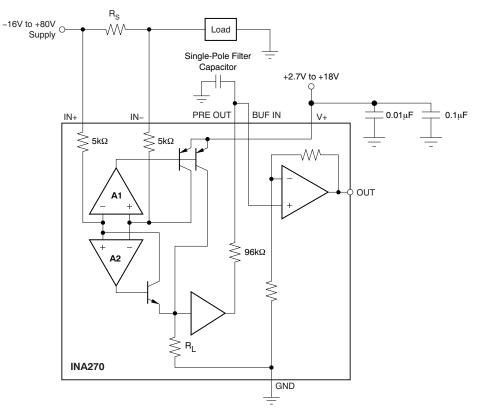


Figure 15. INA270 Basic Connections

8.3.2 Selecting R_S

The value chosen for the shunt resistor, R_S , depends on the application and is a compromise between smallsignal accuracy and maximum permissible voltage loss in the measurement line. High values of R_S provide better accuracy at lower currents by minimizing the effects of offset, while low values of R_S minimize voltage loss in the supply line. For most applications, best performance is attained with an R_S value that provides a full-scale shunt voltage range of 50 mV to 100 mV. Maximum input voltage for accurate measurements is ($V_S - 0.2$) / Gain.

8.3.3 Transient Protection

The –16-V to +80-V common-mode range of the INA270 and INA271 is ideal for withstanding automotive fault conditions ranging from 12-V battery reversal up to +80-V transients because no additional protective components are needed up to those levels. In the event that the INA270 and INA271 are exposed to transients on the inputs in excess of their ratings, external transient absorption with semiconductor transient absorbers (zeners or Transzorbs) are necessary.

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Feature Description (continued)

Use of MOVs or VDRs is not recommended except when they are used in addition to a semiconductor transient absorber. Select the transient absorber such that it never allows the INA270 and INA271 to be exposed to transients greater than 80 V (that is, allow for transient absorber tolerance, as well as additional voltage because of transient absorber dynamic impedance). Despite the use of internal zener-type ESD protection, the INA270 and INA271 are not suited to using external resistors in series with the inputs because the internal gain resistors can vary up to \pm 30%, but are tightly matched (if gain accuracy is not important, then resistors can be added in series with the INA270 and INA271 inputs with two equal resistors on each input).

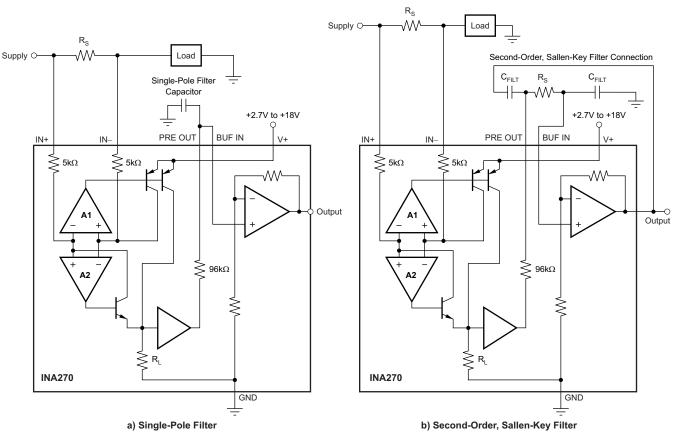
8.4 Device Functional Modes

8.4.1 First- or Second-Order Filtering

The output of the INA270 and INA271 is accurate within the output voltage swing range set by the power-supply pin, V+.

The INA270 and INA271 readily enable the inclusion of filtering between the preamp output and buffer input. Single-pole filtering can be accomplished with a single capacitor because of the 96-k Ω output impedance at PRE OUT on pin 3, as shown in Figure 16a.

The INA270 and INA271 readily lend themselves to second-order Sallen-Key configurations, as shown in Figure 16b. When designing these configurations consider that the PRE OUT 96-k Ω output impedance exhibits an initial variation of ±30% with the addition of a –2200-ppm/°C temperature coefficient.



NOTE: Remember to use the appropriate buffer gain (INA270 = 1.4, INA271 = 2) when designing Sallen-Key configurations.





Device Functional Modes (continued)

8.4.2 Accuracy Variations as a Result of V_{SENSE} and Common-Mode Voltage

The accuracy of the INA270 and INA271 current shunt monitors is a function of two main variables: V_{SENSE} ($V_{IN+} - V_{IN-}$) and common-mode voltage (V_{CM}) relative to the supply voltage, V_S . V_{CM} is expressed as ($V_{IN+} + V_{IN-}$) / 2; however, in practice, V_{CM} is used as the voltage at V_{IN+} because the voltage drop across V_{SENSE} is usually small.

This section addresses the accuracy of these specific operating regions:

Normal Case 1: $V_{SENSE} \ge 20 \text{ mV}$, $V_{CM} \ge V_S$ Normal Case 2: $V_{SENSE} \ge 20 \text{ mV}$, $V_{CM} < V_S$ Low V_{SENSE} Case 1: $V_{SENSE} < 20 \text{ mV}$, $-16 \text{ V} \le V_{CM} < 0$ Low V_{SENSE} Case 2: $V_{SENSE} < 20 \text{ mV}$, $0 \text{ V} \le V_{CM} \le V_S$ Low V_{SENSE} Case 3: $V_{SENSE} < 20 \text{ mV}$, $V_S < V_{CM} \le 80 \text{ V}$

8.4.2.1 Normal Case 1: $V_{SENSE} \ge 20 \text{ mV}, V_{CM} \ge V_S$

This region of operation provides the highest accuracy. Here, the input offset voltage is characterized and measured using a two-step method. First, the gain is determined by Equation 1.

$$G = \frac{V_{OUT1} - V_{OUT2}}{100 \text{mV} - 20 \text{mV}}$$

where

- V_{OUT1} = Output voltage with V_{SENSE} = 100 mV and
- V_{OUT2} = Output voltage with V_{SENSE} = 20 mV.

Then the offset voltage is measured at $V_{SENSE} = 100 \text{ mV}$ and referred to the input (RTI) of the current shunt monitor, as shown in Equation 2.

$$V_{OS}$$
RTI (Referred-To-Input) = $\left(\frac{V_{OUT1}}{G}\right) - 100$ mV (2)

In the *Typical Characteristics*, the *Output Error vs Common-Mode Voltage* curve (Figure 6) shows the highest accuracy for the this region of operation. In this plot, $V_S = 12$ V; for $V_{CM} \ge 12$ V, the output error is at its minimum. This case is also used to create the $V_{SENSE} \ge 20$ mV output specifications in the *Electrical Characteristics* table.

8.4.2.2 Normal Case 2: $V_{SENSE} \ge 20 \text{ mV}, V_{CM} < V_S$

This region of operation has slightly less accuracy than Normal Case 1 as a result of the common-mode operating area in which the device functions, as illustrated in the *Output Error vs Common-Mode Voltage* curve (Figure 6). As noted, for this graph $V_S = 12$ V; for $V_{CM} < 12$ V, the output error increases when V_{CM} becomes less than 12 V, with a typical maximum error of 0.005% at the most negative $V_{CM} = -16$ V.

8.4.2.3 Low V_{SENSE} Case 1: V_{SENSE} < 20 mV, –16 V \leq V_{CM} < 0; and Low V_{SENSE} Case 3: V_{SENSE} < 20 mV, V_S < $V_{CM} \leq$ 80 V

Although the INA270 family of devices are not designed for accurate operation in either of these regions, some applications are exposed to these conditions. For example, when monitoring power supplies that are switched on and off while V_S is still applied to the INA270 or INA271, knowing what the behavior of the devices is in these regions is important.

(1)



Device Functional Modes (continued)

When V_{SENSE} approaches 0 mV, in these V_{CM} regions, the device output accuracy degrades. A larger-thannormal offset can appear at the current shunt monitor output with a typical maximum value of $V_{OUT} = 60$ mV for $V_{SENSE} = 0$ mV. When V_{SENSE} approaches 20 mV, V_{OUT} returns to the expected output value with accuracy as specified in the *Electrical Characteristics*. Figure 17 shows this effect using the INA271 (gain = 20).

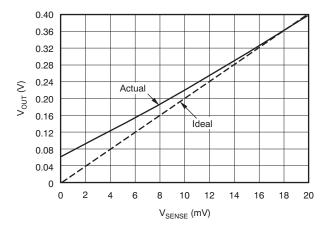
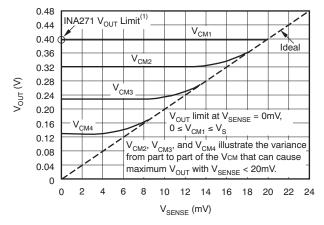


Figure 17. Example For Low V_{SENSE} Cases 1 and 3 (INA271, Gain = 20)

8.4.2.4 Low V_{SENSE} Case 2: $V_{SENSE} < 20 \text{ mV}$, $0 \text{ V} \le V_{CM} \le V_S$

This region of operation is the least accurate for the INA270 family. To achieve the wide input common-mode voltage range, these devices use two op amp front ends in parallel. One op amp front end operates in the positive input common-mode voltage range, and the other in the negative input region. For this case, neither of these two internal amplifiers dominates and overall loop gain is very low. Within this region, V_{OUT} approaches voltages close to linear operation levels for Normal Case 2.

This deviation from linear operation becomes greatest the closer V_{SENSE} approaches 0 V. Within this region, when V_{SENSE} approaches 20 mV, device operation is closer to that described by Normal Case 2. Figure 18 shows this behavior for the INA271. The V_{OUT} maximum peak for this case is determined by maintaining a constant V_S , setting $V_{SENSE} = 0$ mV, and sweeping V_{CM} from 0 V to V_S . The exact V_{CM} at which V_{OUT} peaks during this case varies from device to device. The maximum peak voltage for the INA270 is 0.28 V; for the INA271, the maximum peak voltage is 0.4 V.



NOTE: (1) INA271 V_{OUT} Limit = 0.4V. INA270 V_{OUT} Limit = 0.28V.





9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The INA270 and INA271 measures the voltage developed across a current-sensing resistor when current passes through it. The ability to drive the reference terminal to adjust the functionality of the output signal offers multiple configurations discussed throughout this section. There is also a filtering feature to remove unwanted transients and smooth the output voltage.

9.2 Typical Application

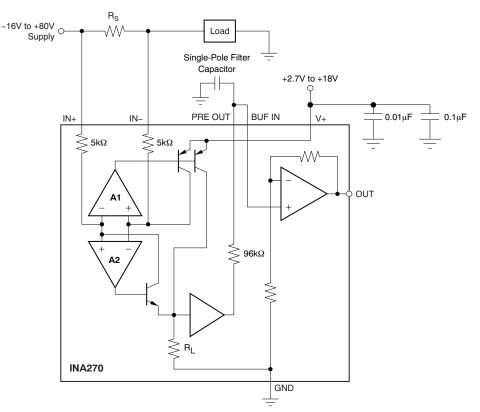


Figure 19. Filtering Configuration

9.2.1 Design Requirements

In this application, the device is configured to measure a triangular periodic current at 10 kHz with filtering. The average current through the shunt is the information that is desired. This current can be either solenoid current or inductor current where current is being pulsed through.

Selecting the capacitor size is based on the lowest frequency component to be filtered out. The amount of signal that is filtered out is dependant on this cutoff frequency. From the cutoff frequency, the attention is 20 dB per decade.

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Typical Application (continued)

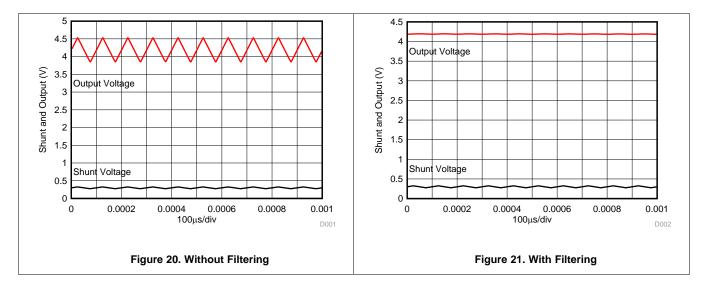
9.2.2 Detailed Design Procedure

Without this filtering capability, an input filter must be used. When series resistance is added to the input, large errors also come into play because the resistance must be large to create a low cutoff frequency. By using a 10-nF capacitor for the single-pole filter capacitor, the 10-kHz signal is averaged. The cutoff frequency made by the capacitor is set at 166 Hz frequency. This frequency is well below the periodic frequency and reduces the ripple on the output and the average current can easily be measured.

9.2.3 Application Curves

Figure 20 shows the output waveform without filtering. The output signal tracks the input signal with a large ripple. If this current is sampled by an ADC, many samples must be taken to average the current digitally. This process takes additional time to sample and average and is very time consuming, thus is unwanted for this application.

Figure 21 shows the output waveform with filtering. The output signal is filtered and the average can easily be measured with a small ripple. If this current is sampled by an ADC, only a few samples must be taken to average. Digital averaging is now not required and the time required is significantly reduced.





10 Power Supply Recommendations

The input circuitry of the INA270 and INA271 can accurately measure beyond its power-supply voltage, V+. For example, the V+ power supply can be 5 V, whereas the load power-supply voltage is up to +80 V. The output voltage range of the OUT terminal, however, is limited by the voltages on the power-supply pin.

10.1 Shutdown

The INA270 and INA271 do not provide a shutdown pin; however, because these devices consume a quiescent current less than 1 mA, they can be powered by either the output of logic gates or by transistor switches to supply power. Driving the gate low shuts down the INA270 and INA271. Use a totem-pole output buffer or gate that can provide sufficient drive along with a 0.1- μ F bypass capacitor, preferably ceramic with good high-frequency characteristics. This gate must have a supply voltage of 3 V or greater because the INA270 and INA271 require a minimum supply greater than 2.7 V. In addition to eliminating quiescent current, this gate also turns off the 10- μ A bias current present at each of the inputs. Note that the IN+ and IN- inputs are able to withstand full common-mode voltage under all powered and under-powered conditions. An example shutdown circuit is shown in Figure 22.

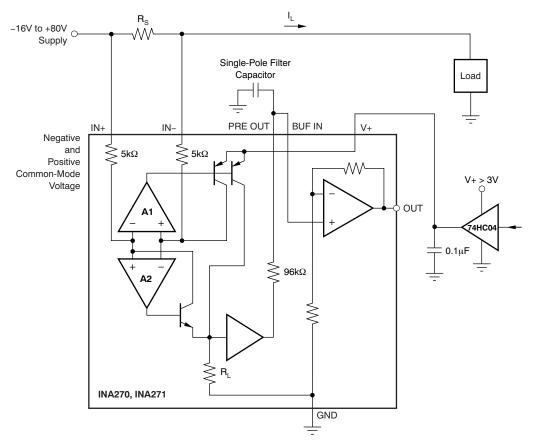


Figure 22. INA270–INA271 Example Shutdown Circuit

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11 Layout

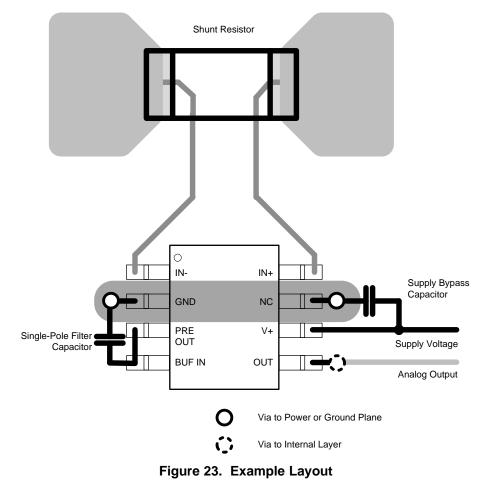
11.1 Layout Guidelines

- Connect the input pins to the sensing resistor using a Kelvin or 4-wire connection. This connection technique
 ensures that only the current-sensing resistor impedance is detected between the input pins. Poor routing of
 the current-sensing resistor commonly results in additional resistance present between the input pins. Given
 the very low ohmic value of the current resistor, any additional high-current carrying impedance can cause
 significant measurement errors.
- Place the power-supply bypass capacitor as closely as possible to the supply and ground pins. The recommended value of this bypass capacitor is 0.1 μF. Additional decoupling capacitance can be added to compensate for noisy or high-impedance power supplies.

11.1.1 RFI and EMI

Attention to good layout practices is always recommended. Keep traces short and, when possible, use a printed circuit board (PCB) ground plane with surface-mount components placed as close to the device pins as possible. Small ceramic capacitors placed directly across amplifier inputs can reduce RFI and EMI sensitivity. PCB layout must locate the amplifier as far away as possible from RFI sources. Sources can include other components in the same system as the amplifier itself, such as inductors (particularly switched inductors handling a lot of current and at high frequencies). RFI can generally be identified as a variation in offset voltage or dc signal levels with changes in the interfering RF signal. If the amplifier cannot be located away from sources of radiation, shielding may be needed. Twisting wire input leads makes them more resistant to RF fields. The difference in input pin location of the INA270 and INA271 versus the INA193 to INA198 may provide different EMI performance.

11.2 Layout Example





12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

INA270 TINA-TI Spice Model, SBOM306

INA270 PSpice Model, SBOM485

INA270 TINA-TI Reference Design, SBOC246

12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to order now.

PARTS	PRODUCT FOLDER	PRODUCT FOLDER ORDER NOW TECHNICAL DOCUMENTS		TOOLS & SOFTWARE	SUPPORT & COMMUNITY	
INA270	Click here	Click here	Click here	Click here	Click here	
INA271	Click here	Click here	Click here	Click here	Click here	

Table 1. Related Links

12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E[™] Online Community *TI's Engineer-to-Engineer (E2E) Community.* Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support TI's Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.4 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
INA270AID	Last	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I270A
	Time Buy								
INA270AIDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I270A
INA270AIDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I270A
INA270AIDRG4.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I270A
INA271AID	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I271A
INA271AID.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I271A
INA271AIDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I271A
INA271AIDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I271A
INA271AIDRG4.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I271A

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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PACKAGE OPTION ADDENDUM

23-May-2025

and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

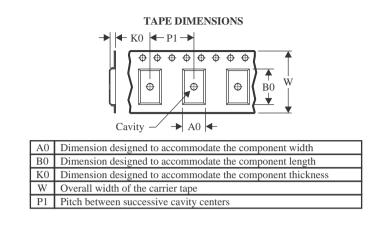
OTHER QUALIFIED VERSIONS OF INA271 :

NOTE: Qualified Version Definitions:



TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions are nominal												
	Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	INA270AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
	INA271AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

23-May-2025



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA270AIDR	SOIC	D	8	2500	350.0	350.0	43.0
INA271AIDR	SOIC	D	8	2500	350.0	350.0	43.0

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
INA270AID	D	SOIC	8	75	505.46	6.76	3810	4
INA271AID	D	SOIC	8	75	505.46	6.76	3810	4
INA271AID.A	D	SOIC	8	75	505.46	6.76	3810	4

D0008A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.

- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



D0008A

EXAMPLE BOARD LAYOUT

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



D0008A

EXAMPLE STENCIL DESIGN

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.



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